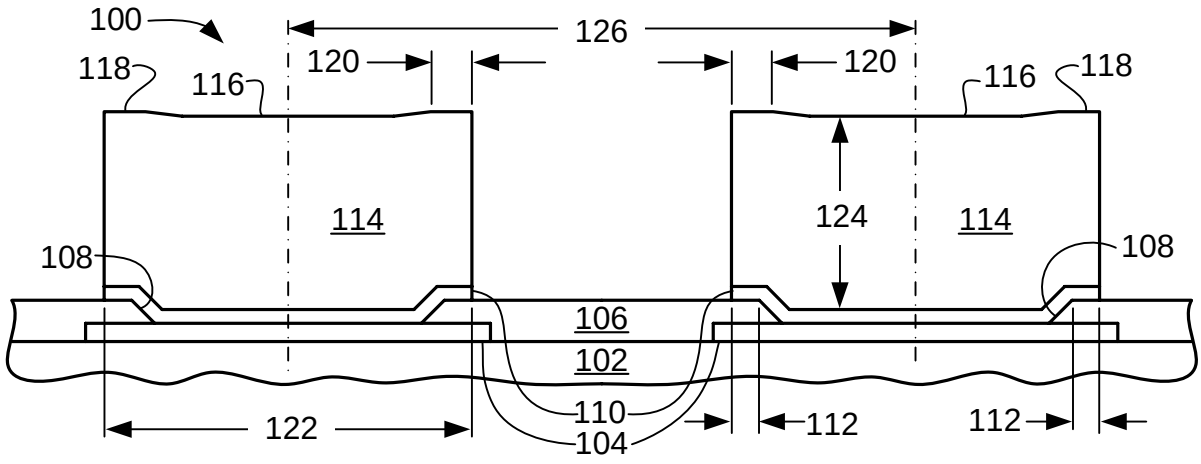


FIG. 1 (PRIOR ART)

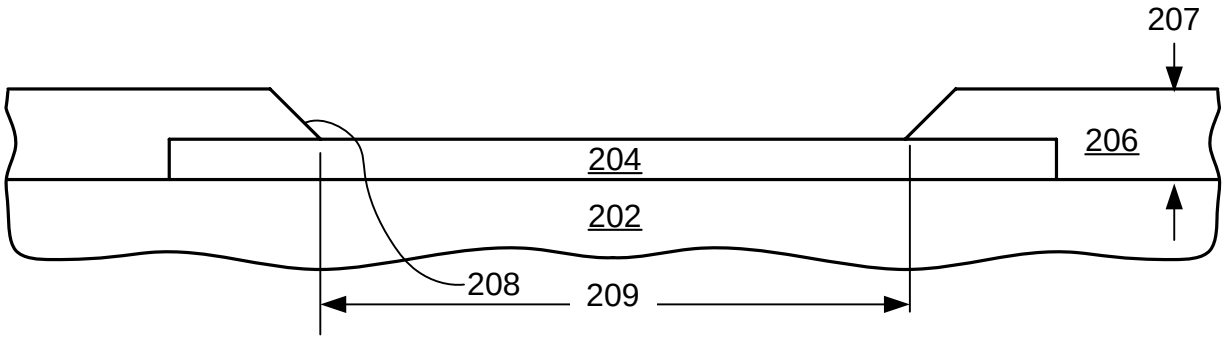


FIG. 2

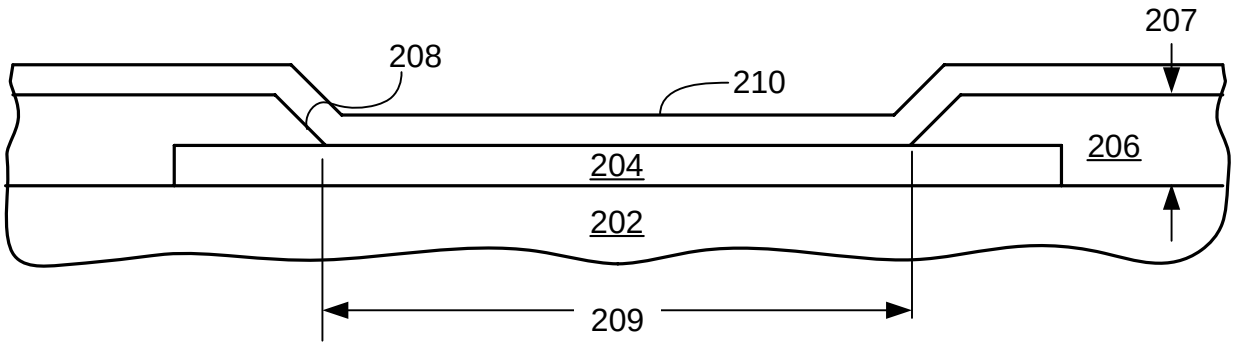


FIG. 3

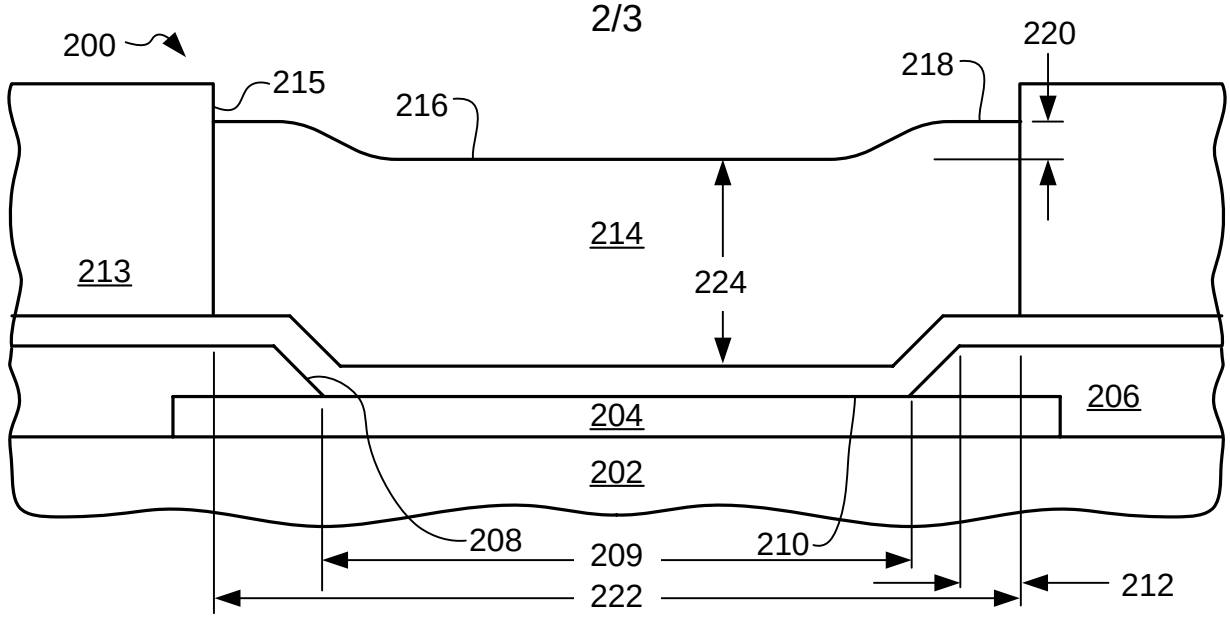

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FIG. 4

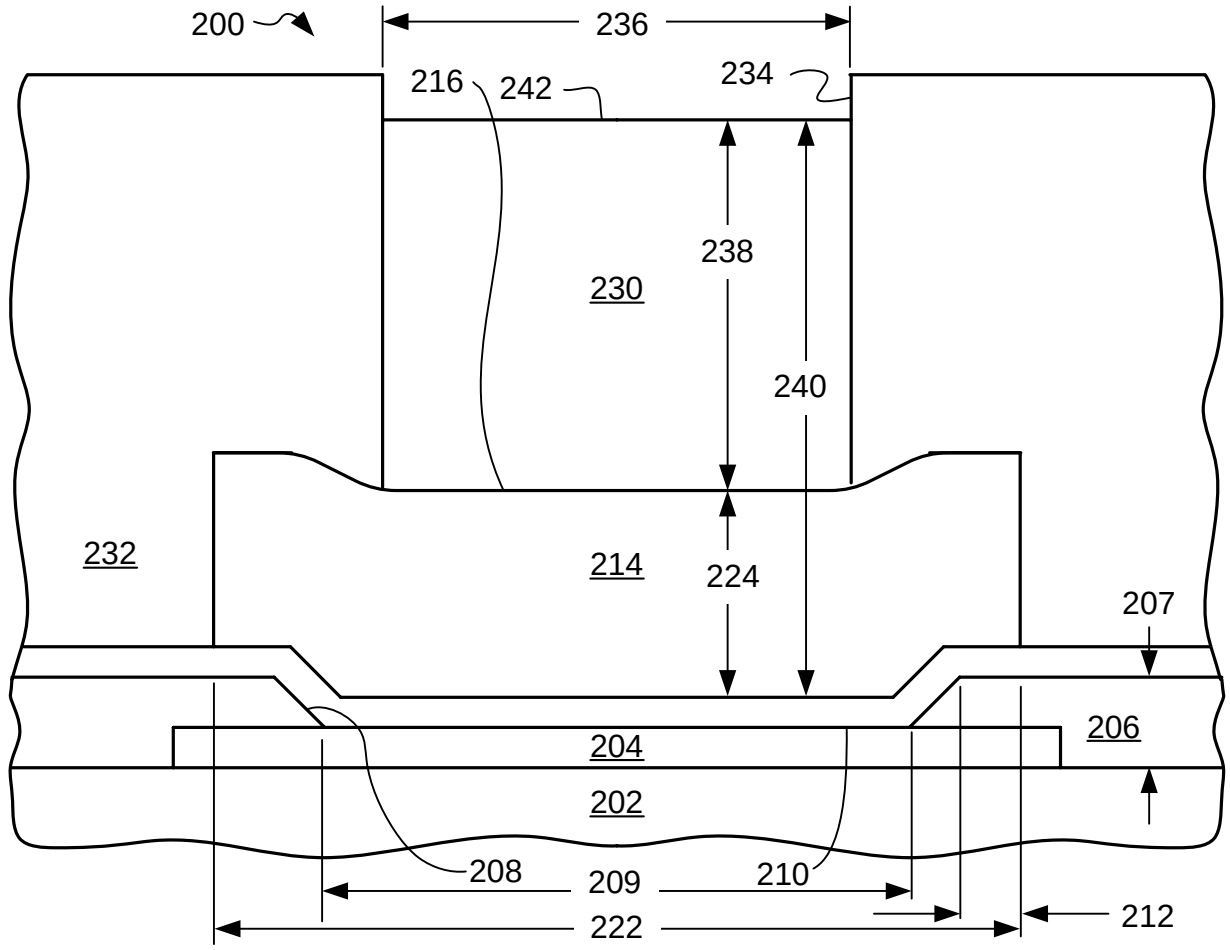

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FIG. 5

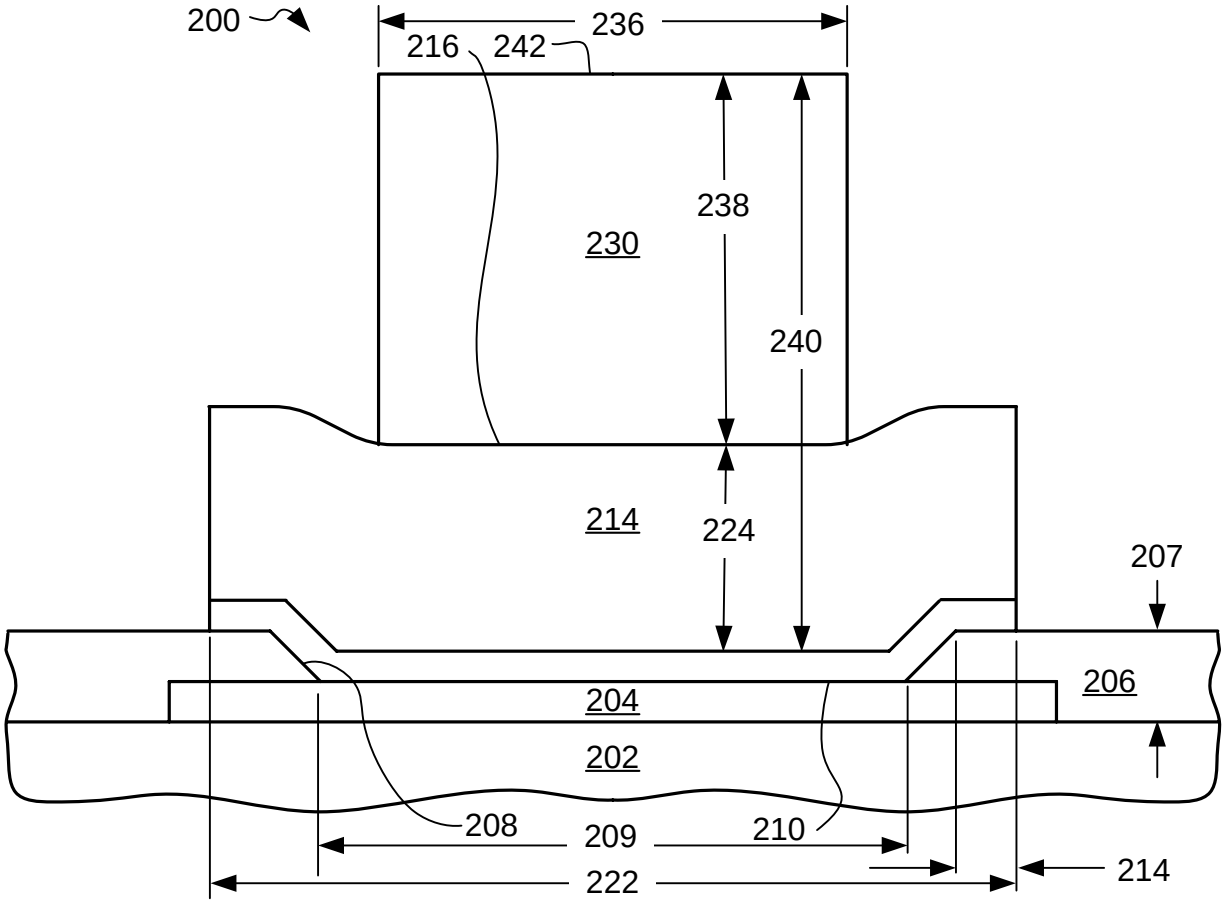

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FIG. 6

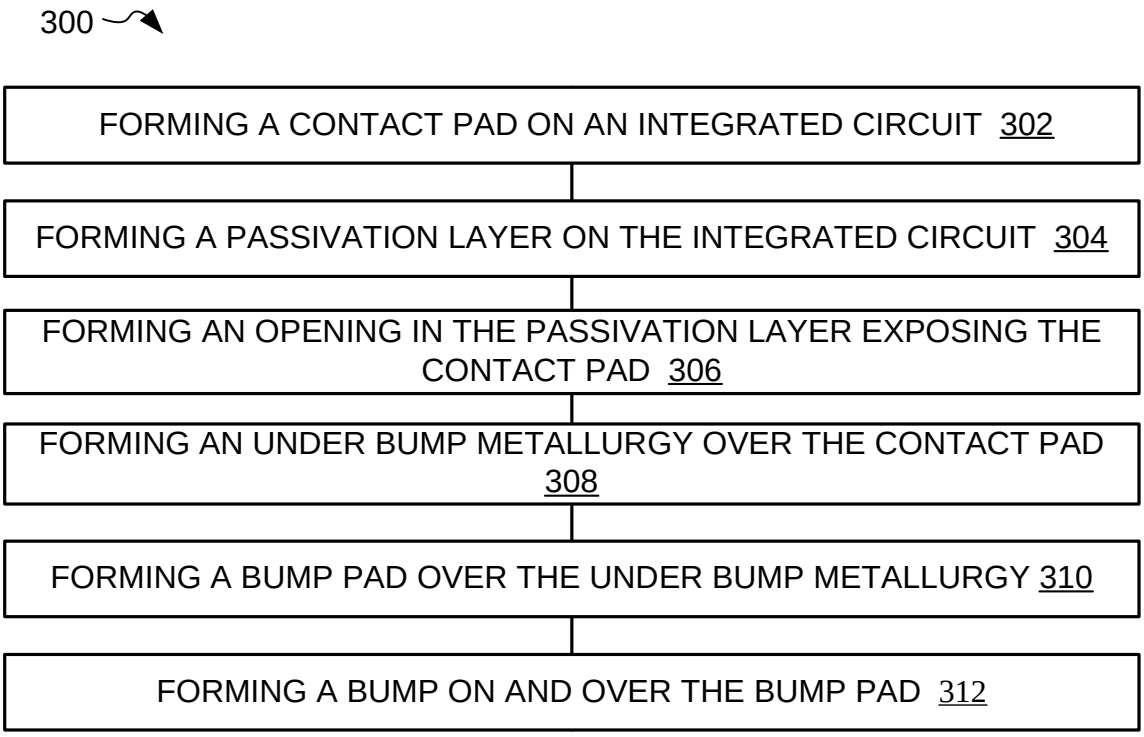

300
FORMING A CONTACT PAD ON AN INTEGRATED CIRCUIT 302
FORMING A PASSIVATION LAYER ON THE INTEGRATED CIRCUIT 304
FORMING AN OPENING IN THE PASSIVATION LAYER EXPOSING THE CONTACT PAD 306
FORMING AN UNDER BUMP METALLURGY OVER THE CONTACT PAD 308
FORMING A BUMP PAD OVER THE UNDER BUMP METALLURGY 310
FORMING A BUMP ON AND OVER THE BUMP PAD 312

FIG. 7